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PATENT  
Attorney Docket YOR19980001  
IBM-278

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Blackshear, et al.  
Serial Number : 09/768,372  
Filing Date : January 23, 2001  
Examiner : J. C. Norris  
Group Art Unit : 2827  
For : STRESS ACCOMMODATION IN ELECTRONIC  
DEVICE INTERCONNECT TECHNOLOGY FOR  
MILLIMETER CONTACT LOCATIONS

To: The Honorable Commissioner of  
Patents and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action (Non Compliant Amendment) dated September 29, 2004, please amend the claims in this application as follows:

Claim 1. (Canceled) In an array of conductive joints between signal pads on a surface of an integrated circuit member of a material having a first thermal expansion responsiveness and corresponding contacts on an aligned wiring support member of a material having a second thermal responsiveness, the improvement comprising: an interface having first and second portions, said first portion of said interface containing an array of elongated conductive joint members each having a contacting area made up of a length contacting dimension and a width contacting dimension and with said length contacting dimension being longer than said width dimension, and, said second portion of said interface having a contacting area approximating the contacting area of said conductive joint members of said first portion and operable to accommodate expansion mismatch stresses in said conductive joint members.